

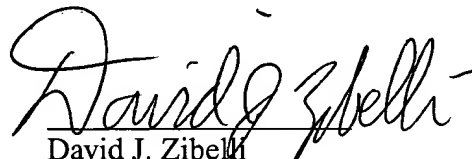
not flat. The claimed first moving means for imparting relative motion in the direction horizontal to polishing surface of the polishing tool between the dressing tool and the polishing tool is recited in claim 1 of the present application. This results in the polishing surface of the polishing tool being ground without being influenced by irregularities on the surface of the dressing tool, thus enabling planerization with high precision of the polishing surface. This is described on page 25, line 22 to page 26, line 2 of the specification. Because this feature is not shown in McHugh, et al., it is respectfully submitted that McHugh, et al., does not anticipate claim 1, or any claims dependent therefrom.

For at least the above reasons, it is submitted that the application is in condition for allowance. Prompt consideration and allowance are earnestly solicited.

The Office is authorized to charge any fees under 37 C.F.R. § 1.16 or § 1.17, and to charge the appropriate fee for a Petition for Extension of Time under 37 C.F.R. § 1.136 to Deposit Account No. 11-0600.

Should there be any questions concerning this matter, the Examiner is invited to contact Applicants' undersigned attorney.

Respectfully submitted,

  
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**APPENDIX**

1. (Amended) A polishing apparatus which imparts relative motion between a layer with a concave portion and a convex portion on a semiconductor wafer [workpiece] and a polishing tool to polish the surface of said workpiece by a polishing surface of said polishing tool, comprising:

a dressing tool for forming a surface roughness on the polishing surface of said polishing tool;

a first moving means for imparting relative motion in a direction horizontal to the polishing surface of said polishing tool between [a grindstone] said dressing tool and said polishing tool;

a second moving means for moving said dressing tool [and/or said polishing tool] in a direction vertical to the polishing surface of said polishing tool; and

a control means for permitting to execute movement caused by said first moving means while controlling a position of said second moving means.

5. (Amended) The polishing apparatus according to claim 1, wherein said control means comprises a detection means for detecting contact of said polishing tool with said dressing tool and controls to stop said second moving means on the basis of the detection of contact between said polishing tool and said [grindstone] dressing tool by said detection means.

10. (Amended) A polishing apparatus which imparts relative motion between a layer with a concave portion and a convex portion [workpiece] and a polishing tool to polish the surface of said workpiece by the polishing surface of said polishing tool, comprising:

a dressing tool for forming a surface roughness on the polishing surface of said polishing tool; and

a means for inhibiting movement of a grindstone in a direction vertical to the polishing surface of said polishing tool.

11. (Amended) [An apparatus] A method for manufacturing a semiconductor for effecting polishing-processing while pressing the thin film surface adhered to the surface of a semiconductor substrate formed with an irregularity pattern to the polishing surface of a polishing tool for relative motion comprising:

[characterized in that] forming [of] a surface roughness with [by] a dressing tool [for forming the surface roughness] on the polishing surface of said polishing tool [is carried out], during a period between [the] polishing processing or during the polishing process, while controlling movement of said dressing tool in a vertical direction with respect to said polishing surface.